

描述 / Descriptions

SOT-23 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-23 Plastic Package.

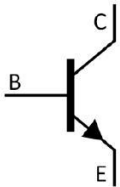
特征 / Features

低电流，低电压。
Low current, low voltage.

用途 / Applications

用于高速开关。
High-speed switching.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : Base PIN 2 : Emitter PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

h_{FE} Range	40~200
Marking	H369

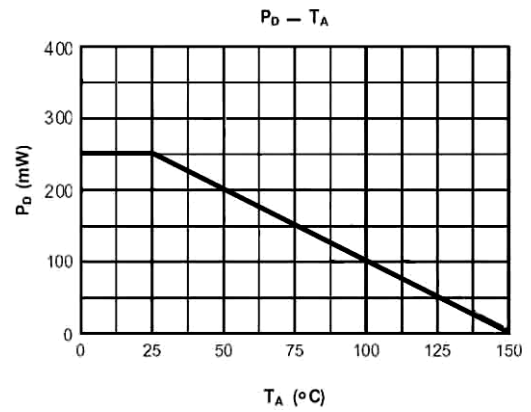
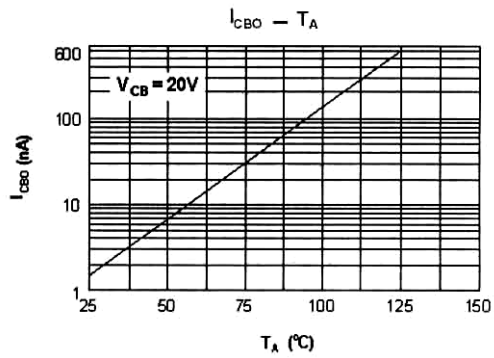
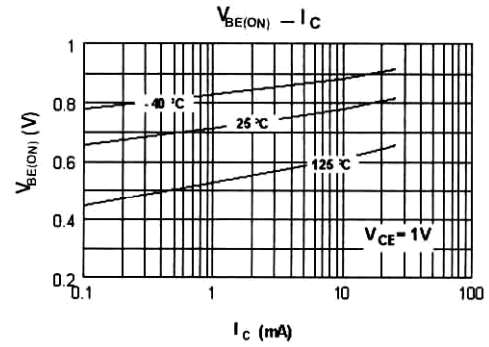
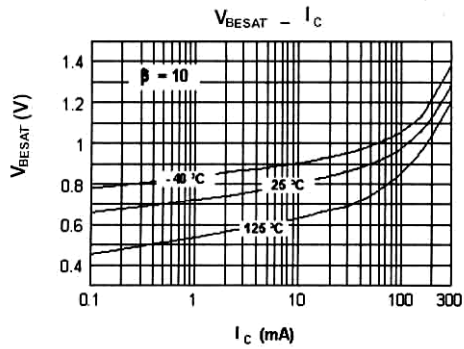
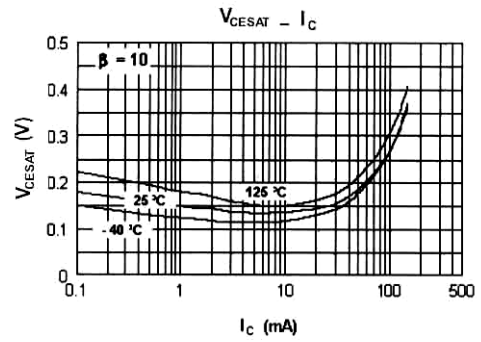
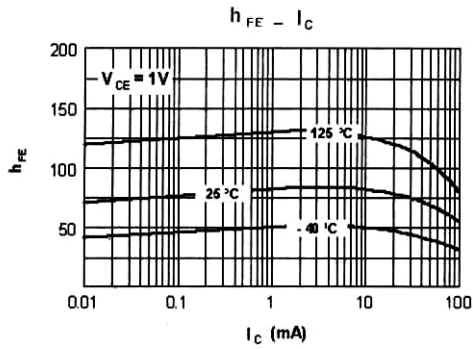
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	15	V
Emitter to Base Voltage	V_{EBO}	4.5	V
Collector Current	I_C	200	mA
Peak Collector Current	I_{CM}	300	mA
Peak Base Current	I_{BM}	100	mA
Collector Power Dissipation	P_C	250	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=20V$ $I_E=0$			0.4	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=4.0V$ $I_C=0$			0.1	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0V$ $I_C=10mA$	40		200	
	$h_{FE(2)}$	$V_{CE}=2.0V$ $I_C=100mA$	20			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=10mA$ $I_B=1.0mA$			0.25	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=10mA$ $I_B=1.0mA$			0.85	V
Collector Capacitance	C_c	$I_E=I_C=0$ $f=1.0MHz$ $V_{CB}=5.0V$			4.0	pF
Emitter Capacitance	C_e	$I_C=I_E=0$ $f=1.0MHz$ $V_{EB}=1.0V$			4.5	pF
Transition Frequency	f_T	$I_C=10mA$ $f=100MHz$ $V_{CE}=10V$	500			MHz
Turn-On Time	t_{on}	$I_C=10mA$ $I_{B1}=3.0mA$ $-I_{B2}=1.5mA$			10	ns
Storage Time	T_{stg}				10	ns
Turn-Off Time	t_{off}				20	ns

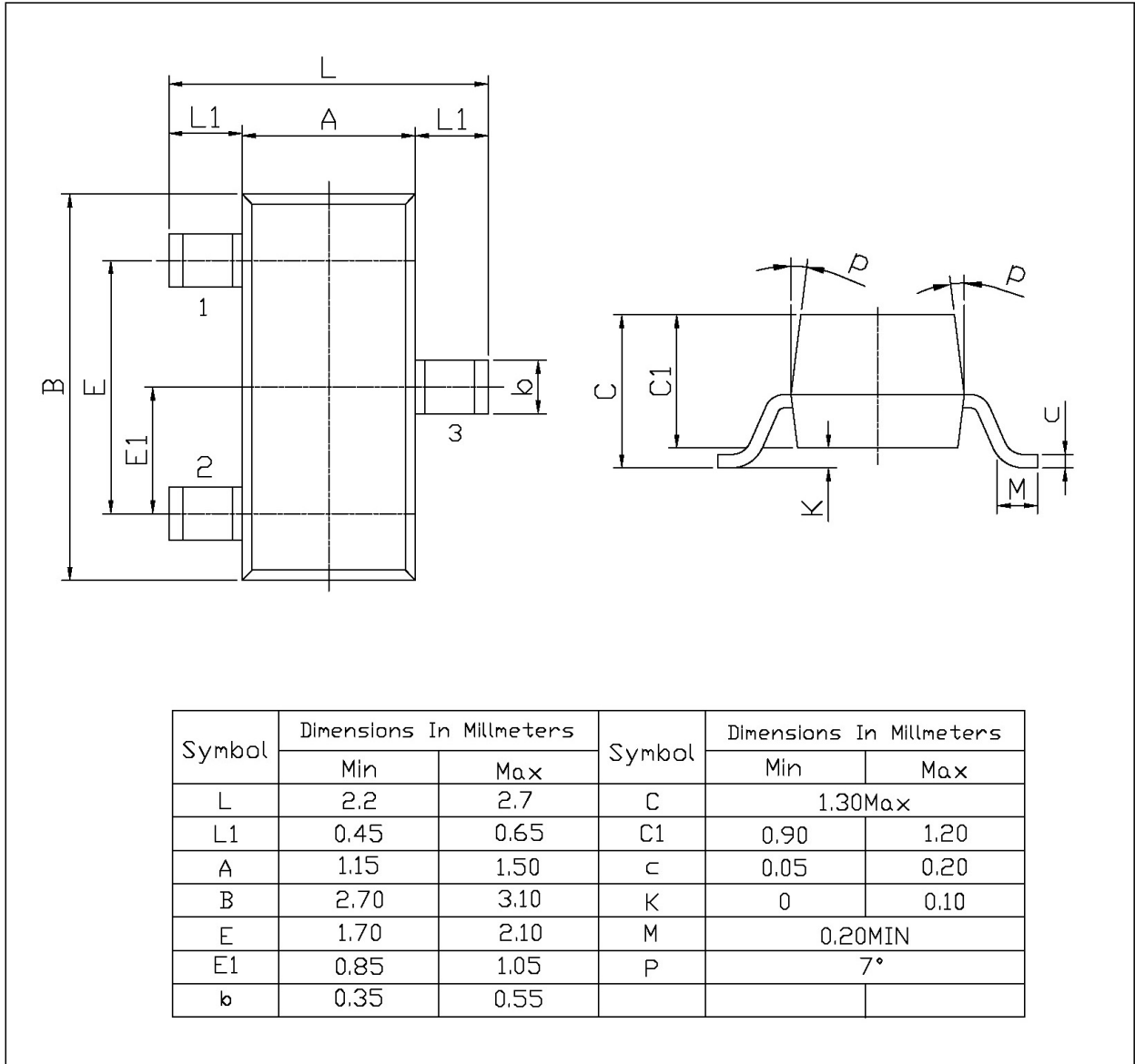
电参数曲线图 / Electrical Characteristic Curve



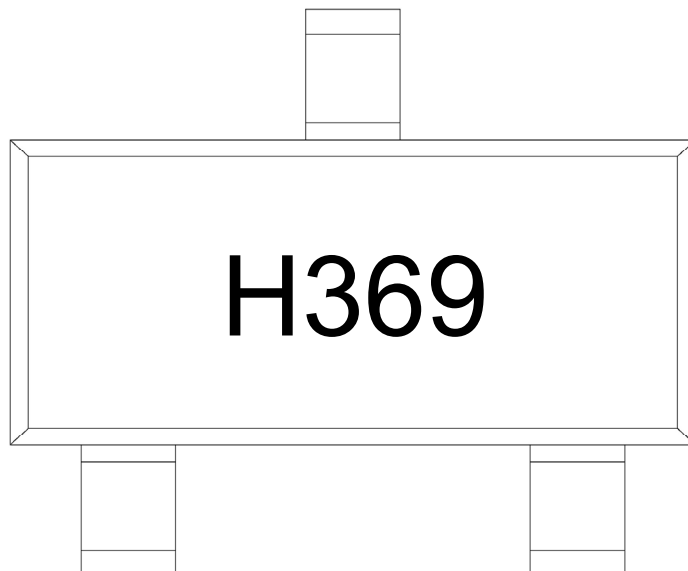
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

369： 为型号代码

Note:

H： Company Code

369： Product Type

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

使用说明 / Notices